10. (Original) A molding method for encapsulating both sides of a PCB module according to claim 1, wherein:

the PCB includes a main portion and a peripheral portion, the main portion having a thickness T_1 and the peripheral portion having a thickness T_2, the thicknesses T_1 and T_2 satisfying the relationship $T_1 > T_2$; and

the upper gate and the lower gate are formed over the peripheral portion.

11. (Original) A molding method for encapsulating both sides of a PCB module according to claim 10, wherein:

the EMC in the upper gate has a thickness T_U and the EMC in the lower gate has a thickness T_L, and further wherein $T_2 + T_U + T_L$ is approximately equal to T_1.

12. (Currently Amended) A molding method for encapsulating both sides of a PCB module according to claim ~~12~~10, wherein:

T_U and T_L are substantially equal.

13.-18. (Cancelled)

***** END CLAIM LISTING *****